

## Specification Sheet

### CIGT160808XMR24MNC (1608 / EIA 0603)



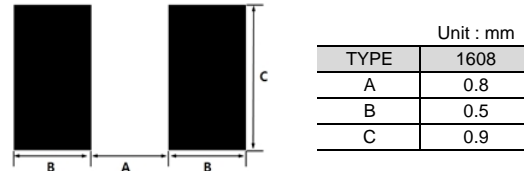
#### APPLICATION

Smart phones, Tablet, Wearable devices, Power converter modules, etc.

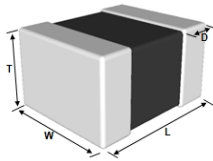
#### FEATURES

Small power inductor for mobile devices  
Low DCR structure and high efficiency inductor for power circuits.  
Monolithic structure for high reliability  
Free of all RoHS-regulated substances  
Halogen free

#### RECOMMENDED LAND PATTERN



#### DIMENSION



TYPE	Dimension [mm]			
	L	W	T	D
1608	1.6±0.2	0.8±0.2	0.8 max	0.3±0.2

#### DESCRIPTION

Part no.	Size [inch/mm]	Thickness [mm] (max)	Inductance [uH]	Inductance tolerance (%)	DC Resistance [mΩ]		Rated DC Current (Isat) [A]		Rated DC Current (Irms) [A]	
					Max.	Typ.	Max.	Typ.	Max.	Typ.
CIGT160808XMR24MNC	0603/1608	0.8	0.24	±20	24	19	4.1	4.6	4.3	4.9

\* Inductance : Measured with a LCR meter 4991A(Agilent) or equivalent (Test Freq. 1MHz, Level 0.1V)

\* DC Resistance : Measured with a Resistance HI-TESTER 3541(HIOKI) or equivalent

\* Maximum allowable DC current : Value defined when DC current flows and the initial value of inductance has decreased by 30% or when current flows and temperature has risen to 40°C whichever is smaller. (Reference: ambient temperature is 25°C±10)

(Isat) : Allowable current in DC saturation : The DC saturation allowable current value is specified when the decrease of the initial inductance value at 30% (Reference: ambient temperature is 25°C±10)

(Irms) : Allowable current of temperature rise : The temperature rise allowable current value is specified when temperature of the inductor is raised 40°C by DC current. (Reference: ambient temperature is 25°C±10)

\* Absolute maximum voltage : Rated Voltage 20V.

\* Operating temperature range : -40 to +125°C (Including self-temperature rise)

#### PRODUCT IDENTIFICATION

**CIG**   **T**   **1608**   **08**   **XM**   **R24**   **M**   **N**   **C**  
**(1)**   **(2)**   **(3)**   **(4)**   **(5)**   **(6)**   **(7)**   **(8)**   **(9)**

(1) Power Inductor

(3) Dimension (1608: 1.6mm x 0.8mm)

(5) Remark (Characterization Code)

(7) Tolerance (M:±20%)

(8) Internal Code

(9) Packaging (C:paper tape, E:embossed tape)

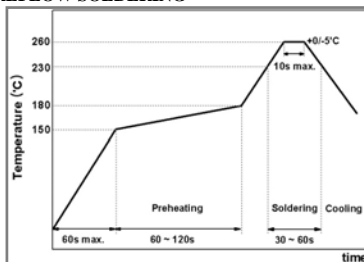
(2) Type (T: Metal Composite Thin Film Type)

(4) Thickness (08: 0.8mm)

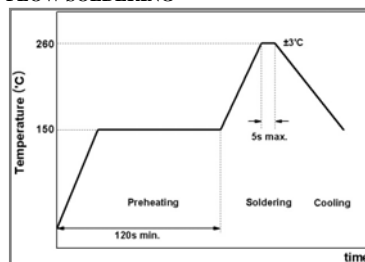
(6) Inductance (R24: 0.24 uH)

#### RECOMMENDED SOLDERING CONDITION

##### REFLOW SOLDERING



##### FLOW SOLDERING



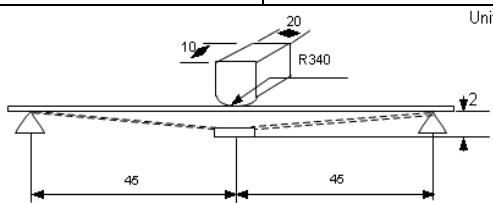
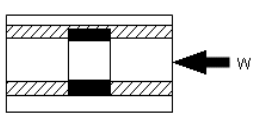
##### IRON SOLDERING

Temperature of Soldering Iron Tip	280°C max.
Preheating Temperature	150°C min.
Temperature Differential	ΔT ≤ 130°C
Soldering Time	3sec max.
Wattage	50W max.

#### PACKAGING

Packaging Style	Quantity(pcs/reel)
Card Board Taping	4000 pcs

## Reliability Test

Item	Specified Value	Test Condition	
Solderability	More than 90% of terminal electrode should be soldered newly.	After being dipped in flux for 4±1 seconds, and preheated at 150~180℃ for 2~3 min, the specimen shall be immersed in solder at 245±5℃ for 4±1 seconds.	
Resistance to Soldering	No mechanical damage. Remaining terminal Electrode: 75% min. Inductance change to be within ±20% to the initial.	After being dipped in flux for 4±1 seconds, and preheated at 150~180℃ for 2~3 min, the specimen shall be immersed in solder at 260±5℃ for 10 ±0.5 seconds.	
Thermal Shock (Temperature Cycle test)	No mechanical damage Inductance change to be within ±20% to the initial.	Repeat 100 cycles under the following conditions. -40±3℃ for 30 min → 85±3℃ for 30 min	
High Temp. Humidity Resistance Test	No mechanical damage Inductance change to be within ±20% to the initial	85±2℃, 85%RH, for 500±12 hours. Measure the test items after leaving at normal temperature and humidity for 24 hours.	
Low Temperature Test	No mechanical damage Inductance change to be within ±20% to the initial.	Solder the sample on PCB. Exposure at -55±2℃ for 500±12 hours. Measure the test items after leaving at normal temperature and humidity for 24hours.	
High Temperature Test	No mechanical damage Inductance change to be within ±20% to the initial.	Solder the sample on PCB. Exposure at 125±2℃ for 500±12 hours. Measure the test items after leaving at normal temperature and humidity for 24hours.	
High Temp. Humidity Resistance Loading Test	No mechanical damage Inductance change to be within ±20% to the initial	85±2℃, 85%RH, Rated Current for 500±12 hours. Measure the test items after leaving at normal temperature and humidity for 24 hours.	
High Temperature Loading Test	No mechanical damage Inductance change to be within ±20% to the initial	85±2℃, Rated Current for 500±12 hours. Measure the test items after leaving at normal temperature and humidity for 24 hours.	
Reflow Test	No mechanical damage Inductance change to be within ±20% to the initial	Peak 260±5℃, 3 times	
Vibration Test	No mechanical damage Inductance change to be within ±20% to the initial.	Solder the sample on PCB. Vibrate as apply 10~55Hz, 1.5mm amplitude for 2 hours in each of three(X,Y,Z) axis (total 6 hours).	
Bending Test	No mechanical damage	Bending Limit; 2mm Test Speed; 1.0mm/sec. Keep the test board at the limit point in 5 sec. PCB thickness : 1.6mm	
			
Terminal Adhesion Test	No indication of peeling shall occur on the terminal electrode.	W(kgf)	TIME(sec)
			0.5
Drop Test	No mechanical damage Inductance change to be within ±20% to the initial.	Random Free Fall test on concrete plate. 1 meter, 10 drops	